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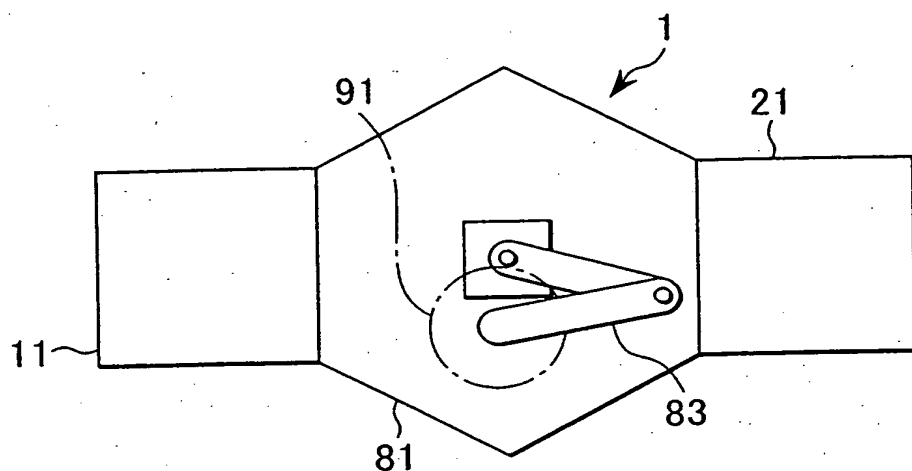
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FIG.1



- 1: FIRST SEMICONDUCTOR MANUFACTURING APPARATUS
- 11: ELECTROLYTIC PLATING CHAMBER
- 21: ELECTROLYTIC POLISHING CHAMBER
- 81: CONVEYING CHAMBER
- 83: CONVEYING INSTRUMENT
- 91: SUBSTRATE

FIG.2

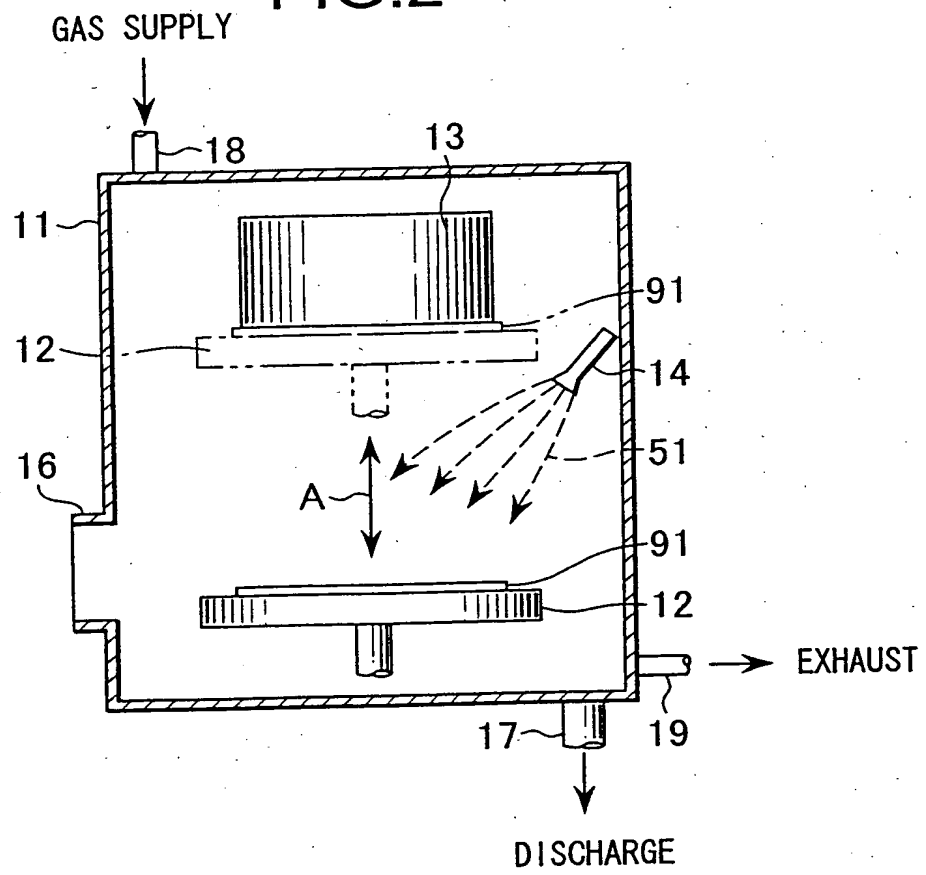


FIG.3

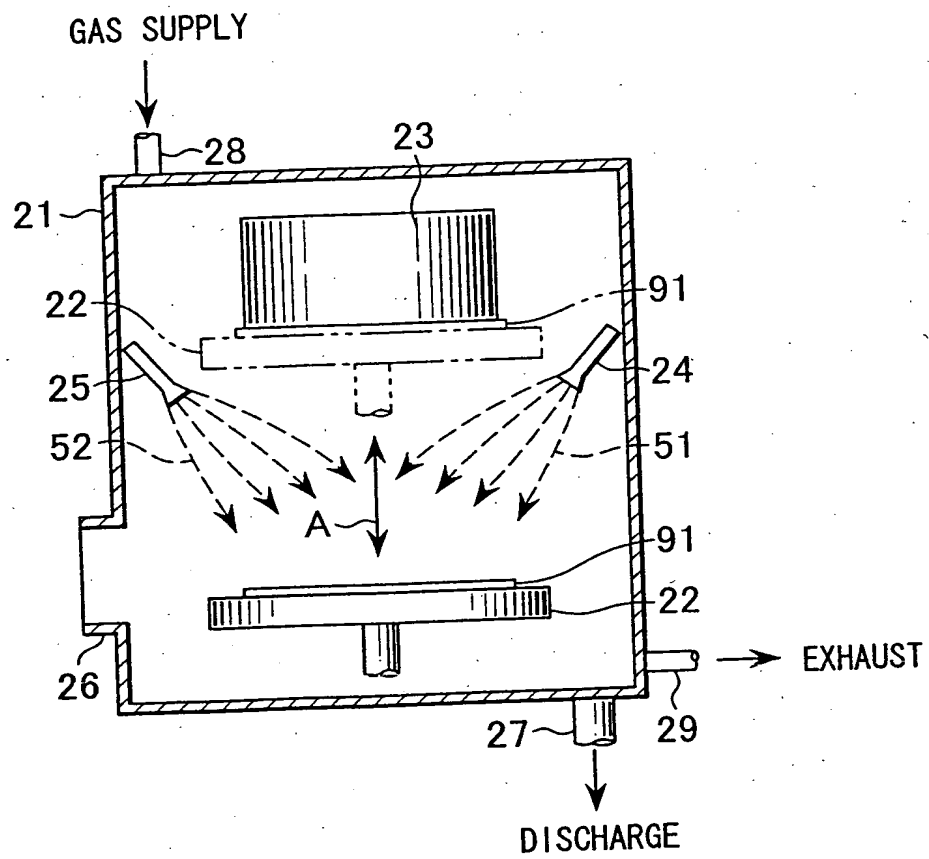


FIG.4

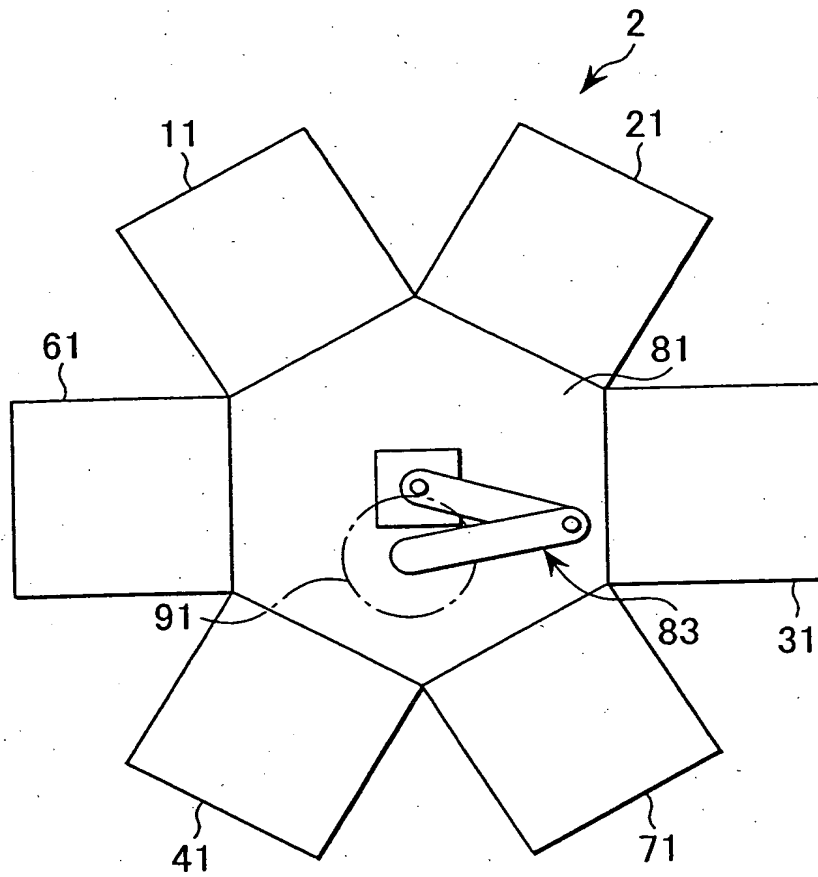


FIG. 5

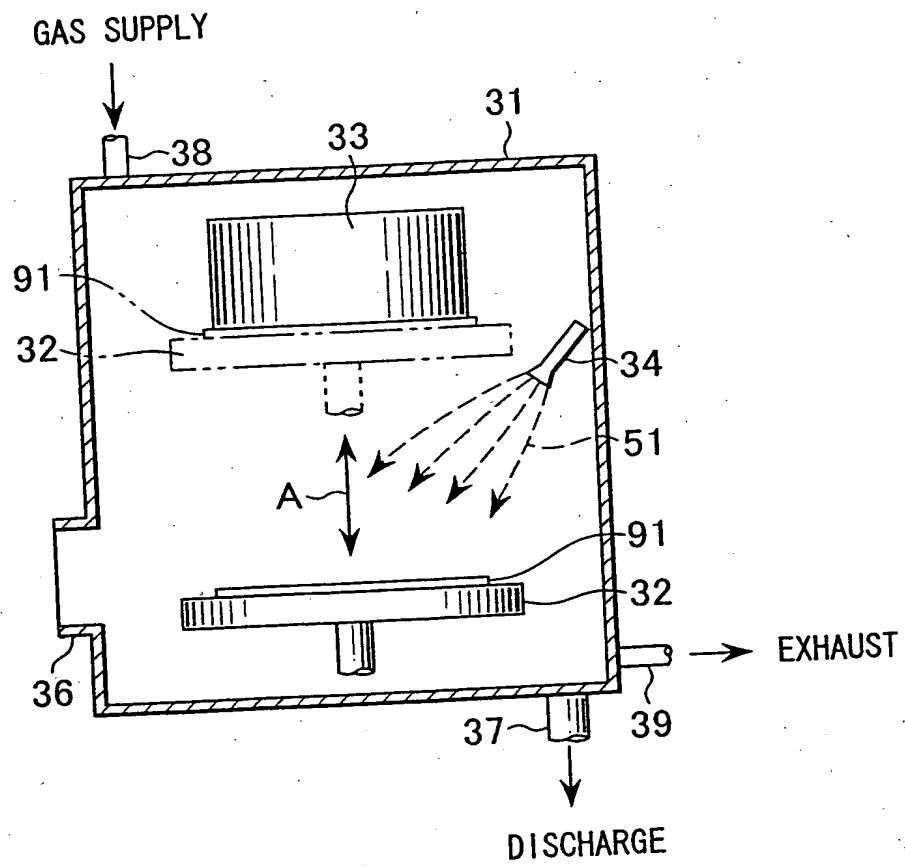


FIG.6

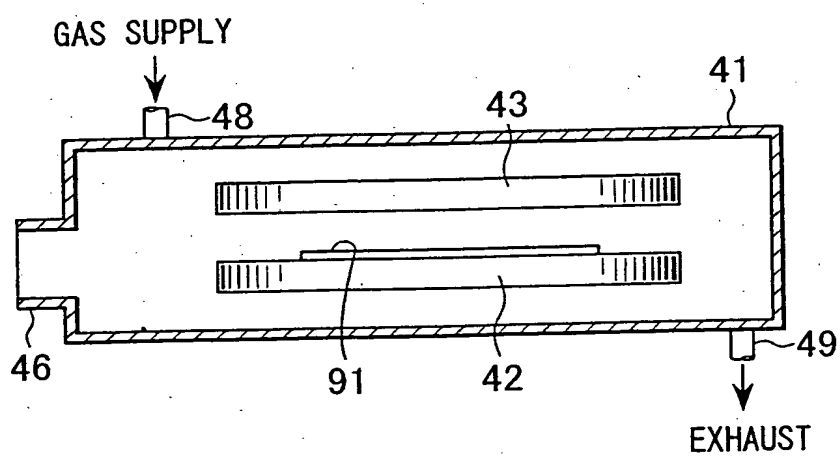


FIG. 7A

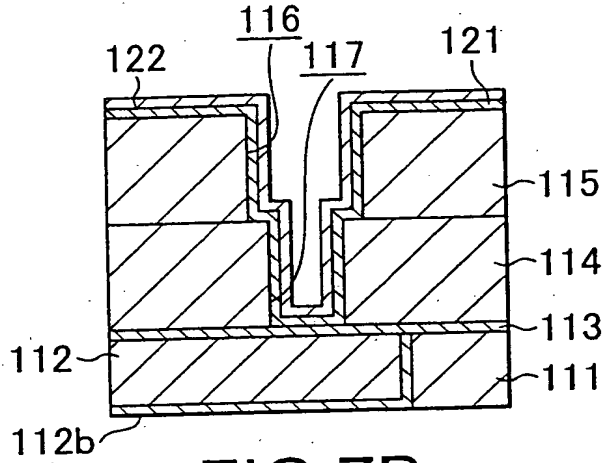


FIG. 7D

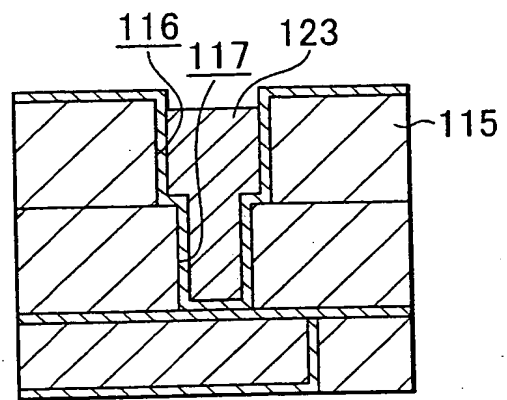


FIG. 7B

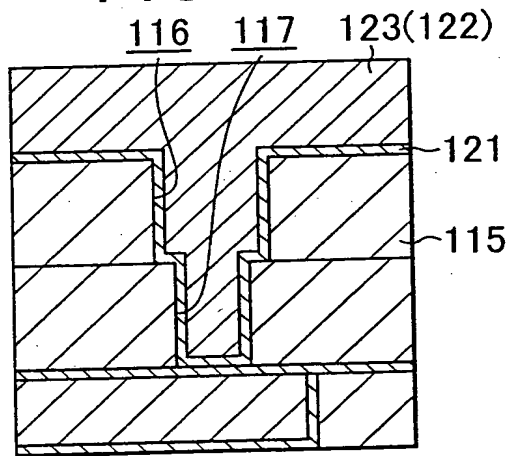


FIG. 7E

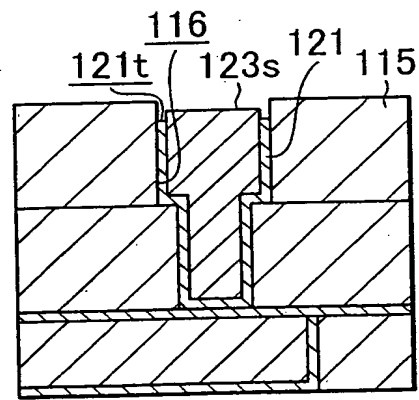


FIG. 7C

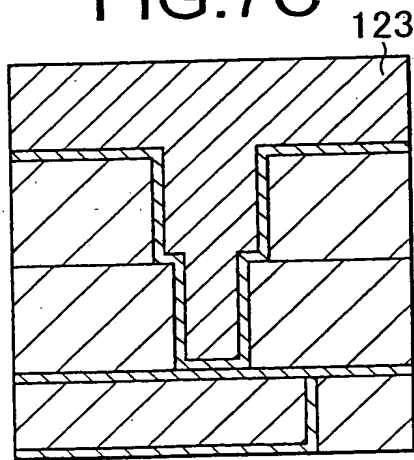


FIG. 7F

